

ICAE 2011

International Conference on Advanced Electromaterials

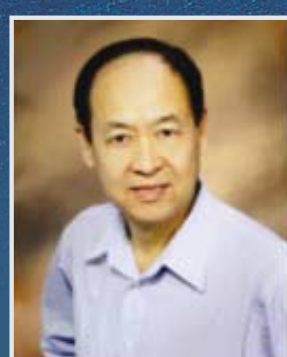
November 7-10, 2011

Ramada Plaza Jeju Hotel, Jeju, Korea

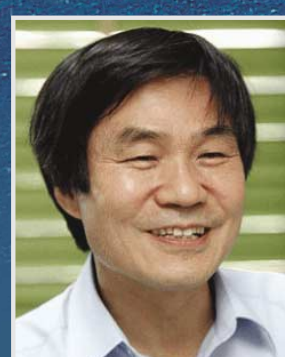
Keynote Speakers



Harry L. Tuller
MIT, USA



Xiao-Qing Yang
Brookhaven
National Lab.,
USA



Jisoon Ihm
Seoul National
Univ., Korea



Hulya Kirkici
Auburn Univ.,
USA



E. Fred Schubert
Rensselaer
Polytechnic
Institute, USA



Masanori
Okuyama
Osaka Univ.,
Japan

Symposium Titles

1. Nanostructured Materials for Sensor Applications (SE)
2. Advanced Materials for Energy Conversion: fuel cell and solar cell (EC)
3. Energy Storage Materials (ES)
4. Nanostructured Materials for Energy Devices (ED)
5. Emerging Nano-based Device Technologies (ND)
6. Ferroelectric, Piezoelectric Materials and Device Applications (FM)
7. Superconducting and Magnetic Materials and Devices (SM)
8. Thin Film Processing and Devices (TF)
9. Advanced Insulating Materials and Condition Monitoring Diagnosis for HV Power Apparatus (HV)
10. LED & OLED Lighting Technology (LT)
11. Nanoscale Interface Devices and Materials for Organic Electronics (OE)
12. Flexible and Printable Electronic Materials and Devices (FE)
13. Advanced Technology for LEDs (LE)
14. Thermal Management Materials, Devices, Processing Technologies and Packages (TM)

Paper Publication

1. Prospective authors are required to submit abstracts by **June 30, 2011.**
2. Authors whose abstracts are accepted will be requested to submit the full paper to the Journal directly by **November 7, 2011.**
3. After peer review and author's revision, all accepted papers will be published as a special issue of the following leading Journals.
 - **Journal of Nanoscience and Nanotechnology (SCI 1.44)**
 - **Journal of Electroceramics (SCI 0.996)**
 - **Journal of Ceramic Processing Research (SCI 0.4)**
 - **Key Engineering Materials (SCOPUS, EI)**
 - **Japanese Journal of Applied Physics (SCI 1.138)**
 - **IEEE Transactions on Dielectrics and Electrical Insulation (SCI 1.082 / in progress)**
 - **Transactions on Electrical and Electronic Materials (Compendex, KCI)**